



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN# 20190718001.1**

**Qualification of additional Fab site (RFAB) and Assembly site (JCET) options for  
select devices  
Change Notification / Sample Request**

**Date:** July 22, 2019  
**To:** PREMIER FARNELL PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team ([PCN\\_ww\\_admin\\_team@list.ti.com](mailto:PCN_ww_admin_team@list.ti.com)). For sample requests or sample related questions, contact your local Field Sales Representative.

PCN Team  
SC Business Services

**20190718001.1**  
**Attachment: 1**

**Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

<b>DEVICE</b>	<b>CUSTOMER PART NUMBER</b>
TPS54202DDCT	null
TPS54202HDDCT	null
TPS54302DDCT	null

Technical details of this Product Change follow on the next page(s).

<b>PCN Number:</b>	20190718001.1	<b>PCN Date:</b>	Jul 22, 2019
<b>Title:</b>	Qualification of additional Fab site (RFAB) and Assembly site (JCET) options for select devices		
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Oct 22, 2019	<b>Estimated Sample Availability:</b>	Date provided at sample request.
<b>Change Type:</b>			
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process
<input type="checkbox"/>	Design	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Electrical Specification
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Mechanical Specification
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Packing/Shipping/Labeling
<input type="checkbox"/>		<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process
<input type="checkbox"/>		<input type="checkbox"/>	Part number change

### PCN Details

#### Description of Change:

Texas Instruments is pleased to announce the qualification of an additional Fab site (RFAB) and Assembly site (JCET) options for the selected devices listed in the "Product Affected" section.

Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
MIHO8	LBC7	200 mm	RFAB	LBC7	300 mm

No Assembly Material Differences between sites. Qual details are provided in the Qual Data Section.

#### Reason for Change:

Continuity of Supply

#### Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

#### Anticipated impact on Material Declaration

<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <a href="#">TI ECO website</a> .
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#### Changes to product identification resulting from this PCN:

##### Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
MIHO8	MH8	JPN	Ibaraki
<b>RFAB</b>	<b>RFB</b>	<b>USA</b>	<b>Richardson</b>

##### Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly Site City
JCET C3	JCE	CHN	Jiangyin
<b>JCET C8</b>	<b>JC8</b>	<b>CHN</b>	<b>Suqian</b>

Sample product shipping label (not actual product label)



MADE IN: Malaysia  
2DC: 20:



(1P) SN74LS07NSR  
(Q) 2000 (D) 0336  
(31T) LOT: 3959047MLA  
(4W) TKY (1T) 7523483SI2  
(P)  
(2P) REV: (V) 0033317  
(20L) CSO: SNE (21L) CCO: USA  
(22L) ASO: MLA (23L) ACO: MYS

MSL 2 / 260C / 1 YEAR SEAL DT  
MSL 1 / 235C / UNLIM 03/29/04

OPT:  
ITEM: 39  
LBL: 5A (L) TO: 1750

**Product Affected:**

PTPS54202DDCR	SN1704026DDCT	TPS54202HDDCR	TPS54302DDCR
PTPS54202DDCT	TPS54202DDCR	TPS54202HDDCT	TPS54302DDCT
SN1704026DDCR	TPS54202DDCT		

**Qualification Report**

SN1704026DDC

Approve Date 26-Jun-2019

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: SN1704026DDC	QBS Product Reference: TPS54202HDDC	QBS Product Reference: TPS54302DDC	QBS Product Reference: TPS563208DDC	QBS Process Reference: TPS65265RHB
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	Pass	Pass
HBM	ESD - HBM	4000V	1/3/0	1/3/0	1/3/0	-	-
CDM	ESD - CDM	1500 V	1/3/0	1/3/0	1/3/0	-	1/3/0
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	1/6/0	-	1/6/0
HTOL	Life Test, 125C	1000 Hours	-	-	1/77/0	-	3/231/0
HTSL	High Temp Storage Bake, 170C	420 Hours	-	-	-	3/231/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	3/231/0	-
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	-	-	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	-	1/77/0	3/231/0	-
PD	Physical Dimensions	(per mechanical drawing)	-	-	-	3/15/0	-
SD	Surface Mount Solderability	Dry Bake 155C (4hours +/-15minutes); Pb-Free Solder	-	-	-	3/66/0	-
SD	Surface Mount Solderability	Dry Bake 155C (4hours +/-15minutes); Pb Solder	-	-	-	3/66/0	-

- QBS: Qual By Similarity
  - Qual Device SN1704026DDC is qualified at LEVEL1-260C
  - Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
  - The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
  - The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
  - The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**  
Qualified Pb-Free (SMT) and Green

# Qualification Report

TPS54202DDC TPS54202HDDC TPS54302DDC  
Approve Date 26-Jun-2019

Qualification Results  
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS54202DDC	Qual Device: TPS54202HDDC	Qual Device: TPS54302DDC	QBS Product Reference: TPS563208DDC	QBS Process Reference: TPS65265RHB
ED	Electrical Characterization	Per Datasheet Parameters	Pass	Pass	Pass	Pass	Pass
HBM	ESD - HBM	4000V	1/3/0	1/3/0	1/3/0	-	-
CDM	ESD - CDM	1500 V	1/3/0	1/3/0	1/3/0	-	1/3/0
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	1/6/0	-	1/6/0
HTOL	Life Test, 125C	1000 Hours	-	-	1/77/0	-	3/231/0
HTSL	High Temp Storage Bake, 170C	420 Hours	-	-	-	3/231/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	3/231/0	-
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	-	-	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	1/77/0	-	1/77/0	3/231/0	-
PD	Physical Dimensions	(per mechanical drawing)	-	-	-	3/15/0	-
SD	Surface Mount Solderability	Dry Bake 155C (4hours +/-15minutes); Pb-Free Solder	-	-	-	3/66/0	-
SD	Surface Mount Solderability	Dry Bake 155C (4hours +/-15minutes); Pb Solder	-	-	-	3/66/0	-

- QBS: Qual By Similarity
- Qual Device TPS54202HDDC is qualified at LEVEL1-260C
- Qual Device TPS54302DDC is qualified at LEVEL1-260C
- Qual Device TPS54202DDC is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
  - The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
  - The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**  
Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
WW PCN Team	<a href="mailto:PCN_ww_admin_team@list.ti.com">PCN_ww_admin_team@list.ti.com</a>

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